

LNPTM THERMOCOMPTM COMPOUND AX06472

AX06472

DESCRIPTION

LNP THERMOCOMP AX06472 compound is based on Acrylonitrile Butadiene Styrene (ABS) resin containing glass fiber and proprietary fillers. Added features of this grade include: Improved Plating Surface and Mechanical Performance targeted for Laser Direct Structuring (LDS) applications.

GENERAL INFORMATION

Features	Dielectrics, Laser Direct Structuring
Fillers	Glass Fiber, Proprietary Filler
Polymer Types	Acrylonitrile Butadiene Styrene (ABS)
Processing Techniques	Injection Molding

INDUSTRY

Automotive
Consumer
Electrical and Electronics
Industrial

SUB INDUSTRY

Automotive Interiors
Personal Accessory
Mobile Phone - Computer - Tablets
Electrical

TYPICAL PROPERTY VALUES

Revision 20231109

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
MECHANICAL ⁽¹⁾			
Tensile Stress, yld, Type I, 5 mm/min	62	MPa	ASTM D638
Tensile Strain, brk, Type I, 5 mm/min	2	%	ASTM D638
Tensile Modulus, 50 mm/min	5930	MPa	ASTM D638
Flexural Stress, brk, 1.3 mm/min, 50 mm span	96	MPa	ASTM D790
Flexural Modulus, 1.3 mm/min, 50 mm span	5380	MPa	ASTM D790
IMPACT ⁽¹⁾			
Izod Impact, unnotched, 23°C	240	J/m	ASTM D4812
Izod Impact, notched, 23°C	42	J/m	ASTM D256
THERMAL ⁽¹⁾			
HDT, 1.82 MPa, 3.2mm, unannealed	96	°C	ASTM D648
Relative Temp Index, Elec ⁽²⁾	60	°C	UL 746B
Relative Temp Index, Mech w/impact ⁽²⁾	60	°C	UL 746B
Relative Temp Index, Mech w/o impact ⁽²⁾	60	°C	UL 746B
PHYSICAL ⁽¹⁾			
Specific Gravity	1.3	-	ASTM D792
Moisture Absorption, (23°C/50% RH/24 hrs)	0.2	%	ASTM D570
Mold Shrinkage, flow, 24 hrs ⁽³⁾	0.4	%	ASTM D955
Mold Shrinkage, xflow, 24 hrs ⁽³⁾	0.5	%	ASTM D955
ELECTRICAL ⁽¹⁾			
Relative Permittivity, 1 GHz	3	-	ASTM D150

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CHEMISTRY THAT MATTERS™

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
Dissipation Factor, 1 GHz	0.003	-	ASTM D150
FLAME CHARACTERISTICS ⁽²⁾			
UL Yellow Card Link	E207780-101345220	-	-
UL Recognized, 94HB Flame Class Rating	≥1.5	mm	UL 94
INJECTION MOLDING ⁽⁴⁾			
Drying Temperature	80	°C	
Drying Time	4	Hrs	
Maximum Moisture Content	0.05 – 0.1	%	
Melt Temperature	260	°C	
Front - Zone 3 Temperature	265 – 275	°C	
Middle - Zone 2 Temperature	230 – 245	°C	
Rear - Zone 1 Temperature	205 – 215	°C	
Mold Temperature	70 – 80	°C	
Back Pressure	0.2 – 0.3	MPa	
Screw Speed	30 – 60	rpm	

(1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.

(2) UL Ratings shown on the technical datasheet might not cover the full range of thicknesses and colors. For details, please see the UL Yellow Card.

(3) Measurements made from laboratory test coupon. Actual shrinkage may vary outside of range due to differences in processing conditions, equipment, part geometry and tool design. It is recommended that mold shrinkage studies be performed with surrogate or legacy tooling prior to cutting tools for new molded article.

(4) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

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